

AMENDMENTS TO THE CLAIMS

A detailed listing of all claims that are, or were, in the present application, irrespective of whether the claim(s) remains under examination in the application are presented below. The claims are presented in ascending order and each includes one status identifier. Those claims not cancelled or withdrawn but amended by the current amendment utilize the following notations for amendment: 1. deleted matter is shown by strikethrough for six or more characters and double brackets for five or less characters; and 2. added matter is shown by underlining.

1. (Previously Presented) A metal-ceramic circuit board comprising a base plate of aluminum or aluminum alloy and a ceramic substrate board, wherein one surface of the ceramic substrate board is bonded directly to the base plate, and the base plate has a proof stress not higher than 320 (MPa) and a thickness not smaller than 1 mm.
2. (Original) The metal-ceramic circuit board according to claim 1, wherein the other surface of the ceramic substrate board has a metal conductive member for an electronic circuit.
3. (Original) The metal-ceramic circuit board according to claim 2, wherein said conductive member is made of a material selected from copper, copper alloy, aluminum and aluminum alloy.
4. (Original) The metal-ceramic circuit board according to claim 1, wherein said ceramic substrate board is made of a material selected from alumina, aluminum nitride and silicon nitride.

5. (Original) The metal-ceramic circuit board according to claim 2, wherein said ceramic substrate board is made of a material selected from alumina, aluminum nitride and silicon nitride.
6. (Original) The metal-ceramic circuit board according to claim 3, wherein said ceramic substrate board is made of a material selected from alumina, aluminum nitride and silicon nitride.
7. (Currently Amended) A power module characterized by comprising a base plate of aluminum or aluminum alloy, a ceramic substrate board, and a semiconductor tip wherein one surface of the ceramic substrate board is bonded directly to the base plate, said semiconductor tip is provided on the other surface of said ceramic substrate board and the base plate has a proof stress not higher than 320 (MPa) and a thickness not smaller than 1 mm.